



# SOT1192-1

plastic thermal enhanced extremely thin small outline  
package; no leads; 4 terminals

8 February 2016

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	HXSON4
Package type industry code	HXSON4
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	20-1-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		0.95	-	1	1.05	mm
E	package width		0.95	-	1	1.05	mm
A	seated height		[tbd]	-	[tbd]	0.5	mm
e	nominal pitch		-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	4	-	



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2. Package outline

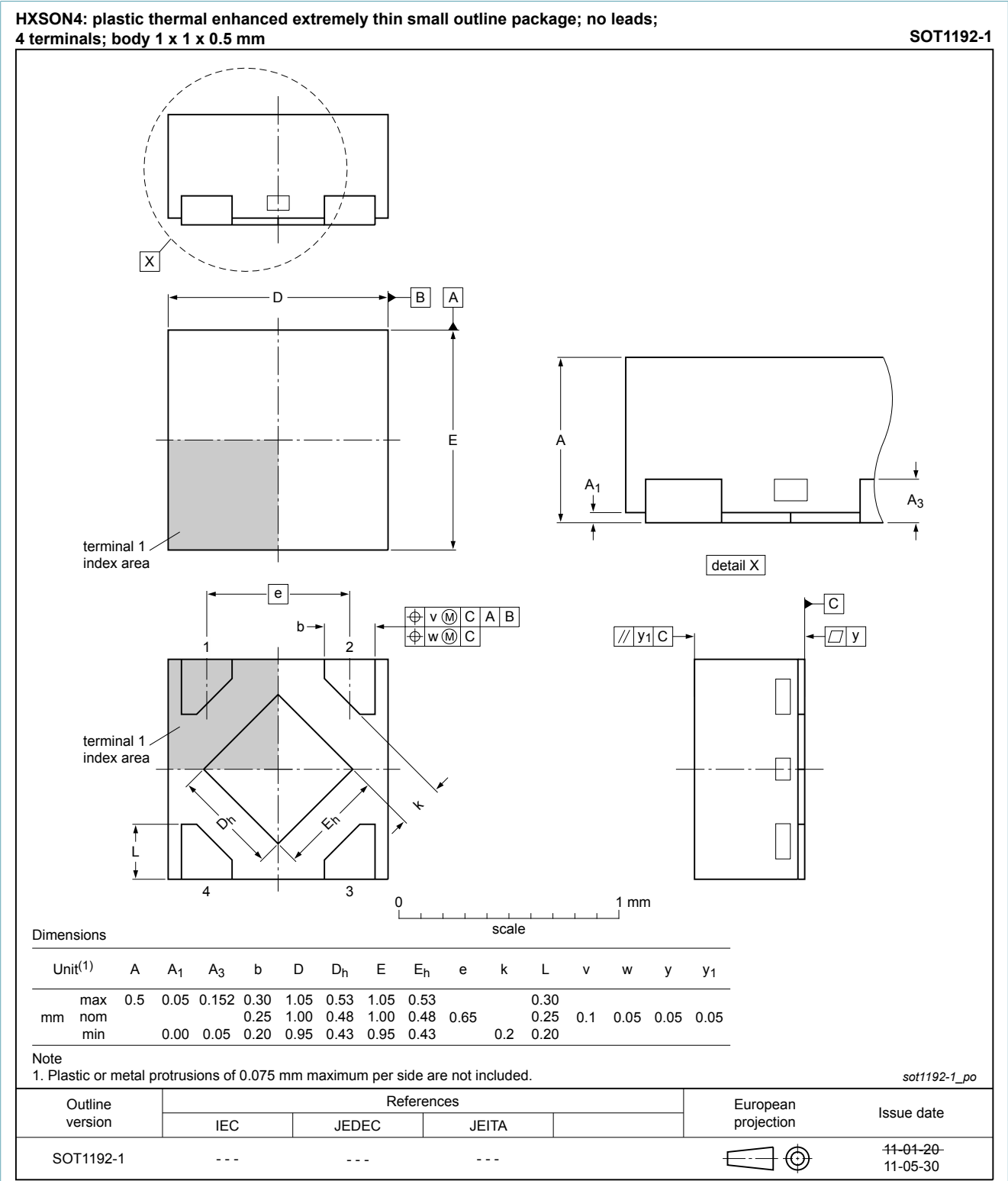
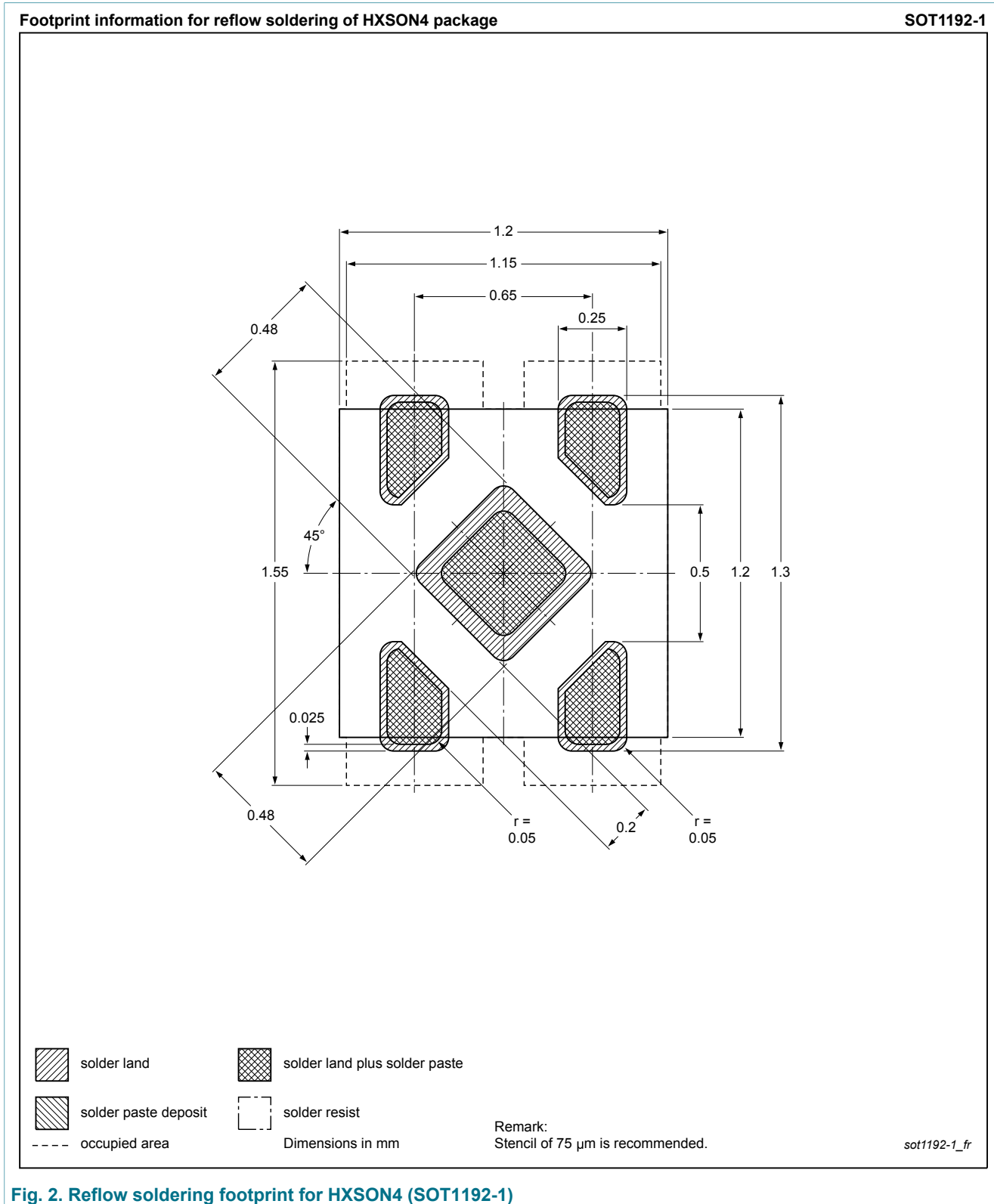


Fig. 1. Package outline HXSON4 (SOT1192-1)

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### 3. Soldering



**Fig. 2. Reflow soldering footprint for HXSON4 (SOT1192-1)**

## 4. Legal information

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